

L Number	Hits	Search Text	DB	Time stamp
1	2289	257/758.ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:13
3	1147	((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
2	1891	(257/758.ccls. and (substrate or wafer)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
4	184	((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 16:52
5	162	((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and (ball or bumps or bump or balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
6	2	6396148.URPN.	USPAT	2004/04/23 17:02
7	4	("5646068"   "5841193"   "6111317"   "6187680").PN.	USPAT	2004/04/23 17:02
8	1	("5841193").PN.	USPAT	2004/04/23 17:16
9	26	5757072.URPN.	USPAT	2004/04/23 17:12
11	0	257/700. ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:21
12	1013	257/700.ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:21
13	922	(257/700.ccls. and (substrate or wafer)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:22
14	403	((257/700.ccls. and (substrate or wafer)) and (@ad<20011231)) and (ball or bumps or bump or balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:22
15	355	((257/700.ccls. and (substrate or wafer)) and (@ad<20011231)) and (ball or bumps or bump or balls)) not (((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and (ball or bumps or bump or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:22
16	368	((257/700.ccls. and (substrate or wafer)) and (@ad<20011231)) and (ball or bumps or bump or balls)) not (((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and package )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 17:23

17	1826	438/106.ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:13
18	749	438/107.ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:13
19	1724	438/612.ccls. and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:13
20	3979	(438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:13
21	1514	((438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))) and (dielectric or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
22	1178	((((438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))) and (dielectric or polyimide)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
23	763	(((((438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))) and (dielectric or polyimide)) and (@ad<20011231)) and (ball or bumps or bump or balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:14
24	9242507	(((((438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))) and (dielectric or polyimide)) and (@ad<20011231)) and (ball or bumps or bump or balls)) no (((257/700.ccls. and (substrate or wafer)) and (@ad<20011231)) and (ball or bumps or bump or balls)) not (((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and package ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:15
25	756	(((((438/106.ccls. and (substrate or wafer)) or (438/107.ccls. and (substrate or wafer)) or (438/612.ccls. and (substrate or wafer))) and (dielectric or polyimide)) and (@ad<20011231)) and (ball or bumps or bump or balls)) not (((257/700.ccls. and (substrate or wafer)) and (@ad<20011231)) and (ball or bumps or bump or balls)) not (((257/758.ccls. and (substrate or wafer)) and (@ad<20011231)) and (dielectric or polyimide)) and package ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/23 18:15
26	11	("5353498"   "5422513"   "5455457"   "5497033"   "5514906"   "5527741"   "5703400"   "5745984"   "5895229"   "6154366"   "6184570").PN.	USPAT	2004/04/23 18:23
27	14	6154366.URPN.	USPAT	2004/04/23 18:25
28	13	("5111278"   "5291066"   "5353498"   "5422513"   "5497033"   "5527741"   "5703400"   "5745984"   "5856705"   "5977639"   "5998859"   "6154366"   "6423566").PN.	USPAT	2004/04/23 18:29

29	0	6713859.URPN.	USPAT	2004/04/23 18:30
30	0	6713859.URPN.	USPAT	2004/04/23 18:30